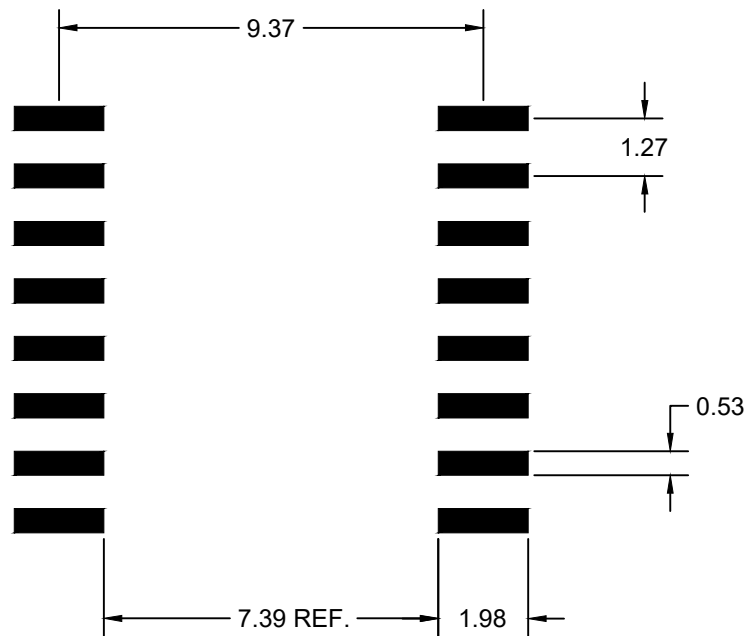


RECOMMENDED LAND PATTERN



PACKAGE OVERLAY

PKG. CODES
[W16+1]
[W16+2]
[W16+3]
[W16+4F]
[W16+6]
[W16+7]
[W16+10]
[W16+11]
[W16+12]
[W16+H2]
[W16M+3]
[W16M+6]
[W16MK+1]
[W16M+8]
[W16M+9]
[W16M+10]
[W16MS+11]
[W16MS+12]
[W16MS+12C]
[W16MS+13]
[W16MS+13C]
[W16MS+14]

NOTES:

1. REFERENCE PKG. OUTLINE: 21-0042
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: ± 0.02 MM.
4. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
5. ALL DIMENSIONS IN MM.

—DRAWING NOT TO SCALE—



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <http://www.maxim-ic.com/support> for further questions.

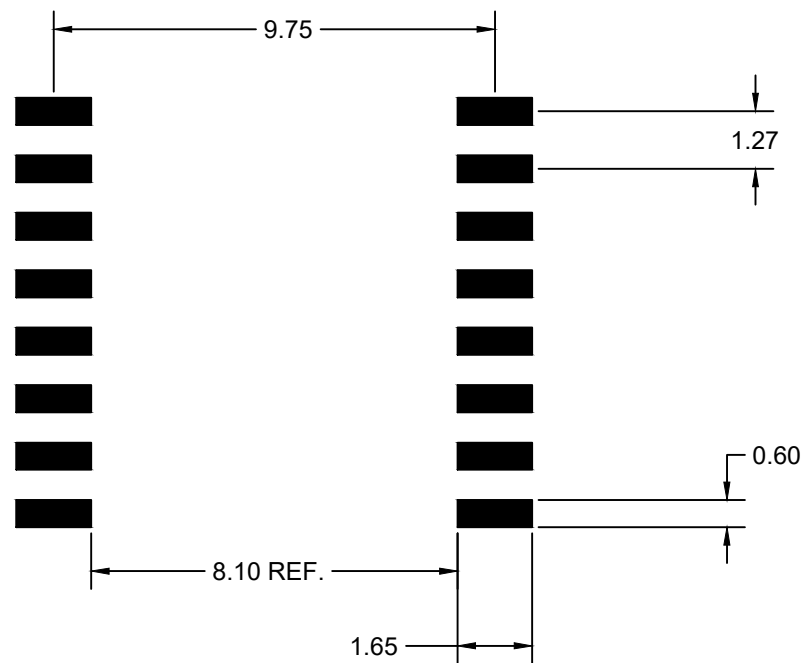
TITLE:
PACKAGE LAND PATTERN,
[W16] 0.300" SOIC, 16 LEADS

APPROVAL
ROHINI KESAVAN

DOCUMENT CONTROL NO.
90-0107

REV. 1
L 2

OPTION FOR IMPROVED HV ISOLATION
(CLEARANCE/CREEPAGE OF 8.1MM)



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